

U.S. Patent Application Serial No.: 10/531,075
Response filed March 18, 2011
Reply to OA dated October 22, 2010

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A heat shielding material for an agricultural and horticultural facility, comprising:

a heat shield layer comprising a substrate resin and a heat shield filler in the form of particles kneaded in said substrate resin, said heat shield layer being in the form of a single plate having a thickness of 2 to 15 mm,

wherein said substrate resin in said heat shield layer is polyvinyl chloride resin;

said heat shield filler in said heat shield layer is lanthanum hexaboride, the content of said heat shield filler in said heat shield layer is in the range of 0.01 to 1 g/m²; and

said heat shielding material for an agricultural and horticultural facility has a visible light transmittance in the range of 30 to 90% and a solar radiation transmittance in the range of 10 to 80%,

wherein said visible light transmittance is set to be larger by 10% or above than said solar radiation transmittance, and

wherein said heat shielding material for an agricultural and horticultural facility has an ultraviolet light transmittance at a wavelength of 290 to 320 nm.

Claims 2-5 (Canceled).

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Claim 6 (Previously Presented): The heat shielding material for an agricultural and horticultural facility of claim 1, wherein said heat shielding material for an agricultural and horticultural facility has a visible light transmittance in the range of 60 to 90% and a solar radiation transmittance in the range of 10 to 70%.

Claim 7 (Previously Presented): The heat shielding material for an agricultural and horticultural facility of claim 6, wherein said heat shield filler is in a form of fine particles having a particle diameter in a range of 100 nm or greater and 200 nm or less uniformly dispersed within the heat shield layer.

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